



1763

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

**Yao, et al.**

Serial No. **09/457,929**

Filed: **December 8, 1999**

**For: WAFER CARRIER AND  
SEMICONDUCTOR APPARATUS FOR  
PROCESSING A SEMICONDUCTOR  
SUBSTRATE**

Examiner: **Jeffrie R. Lund**

Group Art Unit: **1763**

San Francisco, CA 94111

Date: **March 4, 2002**

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I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as First Class Mail in an envelope addressed to: Box Missing Parts, Commissioner of Patents and Trademarks, Washington, D.C. 20231 on *March 4, 2002*.

Signed:

*Kari Bateman*  
Kari Bateman

TRANSMITTAL LETTER

Assistant Commissioner for Patents  
Washington, DC 20231

Sir:

Please find enclosed the following documents relating to the subject patent application:

- ☒ [X] Amendment in response to Office Action dated September 4, 2001;
- ☒ [X] Petition for Extension of Time (Three Months);
- ☒ [X] Check No. 008067 in the amount of \$920.00 (\$920 for Petition for Three Month Extension of Time for large entity);
- ☒ [X] Please charge any additional fees or credit any overpayment to Deposit Account No. 06-1300 (Order No. A-64873-1/AJT/MSS). A copy of this sheet is enclosed for such purpose.
- ☒ [X] Return Postcard.

Respectfully submitted,

By: *Maria S. Swiatek*  
Maria S. Swiatek, Reg. No. 37,244

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Signed: Kari Bauman

Kari Bauman

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AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

The following is in response to the Office Action dated September 4, 2001. Please amend the referenced application as follows:

IN THE SPECIFICATION

Please replace the paragraph beginning at page 7, line 3, with the following rewritten paragraph:

To maintain the desirable line or point contact with the peripheral edge of the wafer and to provide secure support of the wafer, the thermal expansion of the wafer carrier is considered. Preferably, little thermal expansion occurs during the process so that the desired angle of the incline is preserved. Specifically, the wafer carrier is comprised of a material having a coefficient of thermal expansion in the range of  $2.6 \times 10^{-6}/^{\circ}\text{C}$  to  $5 \times 10^{-6}/^{\circ}\text{C}$ , with the lower values preferred. Materials with